ABGOGIATION CONNECTING ELECTRONICS (MOUSTRIESS) MOUSTRIESS	kburn. Illinois. A	ll rights reserved untions.	under both This d	locumen parts, the	t is a declaration ended	on of the su	ibstances s all lowe	within the manufacture level materials for w	urer listed which the	item. Note manufactu	e: if the iter arer has eng	m is an assem gineering resp	bly with lower onsibility.	
IPC Web Site for Information o http://www.ipc.org/IPC-175x	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and M					Afg Inform	nation			
Supplier Information														
npany name* Company unique ID				Unique ID Authority					Respon	Response Date*				
onsemi										2024-05-21				
Contact Name	Title - Contact			Pł	Phone - Contact*				Email	Email - Contact*				
Product-Env-Stewards	Product Envi		Ν	NA				Product-Env-Stewards@onsemi.com						
Authorized Representative*	rized Representative* Title - Representative			Phone - Representative*				Email	Email - Representative*					
Product-Env-Stewards Product Enviro Compliance				NA					Produ	Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr It	em Number	Mfr Item Name		E	Effective Date	Version]	Manufacturing Site		Weight*	UC	OM	Unit Type	
NCP7	718AMT250TBG 300 mA Low Iq, W WDFN6		Wide Input Voltage LI	DO - 2	2024-05-21 T		TH6		9.6	mg	5	Each		
Manufacturing Proccess Information														
Terminal Plating / Grid Array Material	Terminal Base	Alloy	J-STD-020 MSL Ratin	ıg	Peak Process Body Temperatur		re Max Time at Peak	c Tempera	ature Nu	mber of Re	eflow Cycles			
Matte Tin (Sn) - annealed CU Alloy 1			1		260		С	30	seco	nds 3				
Comments														
evel 1 - maximum time at peak temperature during	soldering is 10-3	0 seconds												
for more information regarding material composition	n please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl thalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted								
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.4	mg	Supplier	Silicon (Si)	7440-21-3		0.4	mg
Die Attach	0.1	mg	Supplier	Isobornyl Methacrylate	7534-94-3		0.006	mg
			Supplier	Silver (Ag)	7440-22-4		0.0815	mg
			Supplier	Isobornyl Acrylate	5888-33-5		0.006	mg
			Supplier	Misc.	Proprietary Data		0.0005	mg
			Supplier	Tricyclo[5.2.1.02,6]decanedimethanol Diacrylate (C18H24O4)	42594-17-2		0.006	mg
Lead Frame	4.22	mg	Supplier	Tin (Sn)	7440-31-5		0.0105	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0093	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0105	mg
			Supplier	Copper (Cu)	7440-50-8		4.1896	mg
Mold Compound-Black	4.65	mg		Epoxy resin	proprietary data		0.2325	mg
			Supplier	Phenolic Resin	Proprietary Data		0.1069	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.2325	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0186	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.1069	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		3.9525	mg
Plating	0.2	mg	Supplier	Tin (Sn)	7440-31-5		0.2	mg
Wire Bond - Au	0.03	mg	Supplier	Gold (Au)	7440-57-5		0.03	mg